



Dr. Bo Un Yoon

(Samsung Electronics, Korea)

Bo Un Yoon is a Fellow at Samsung Electronics, specializing in the development of Chemical Mechanical Polishing (CMP) processes, materials, and equipment crucial for next-generation DRAM, Flash, and Logic devices. He earned his B.S., M.S., and Ph.D. degrees in Chemistry from Seoul National University in 1988, 1990, and 1996, respectively.

Throughout his career at Samsung Electronics, starting as a CMP Engineer in 1996 and progressing through roles as CMP Part Leader (2000–2012) and Master (2012–2020), he has demonstrated consistent leadership and innovation. Currently, as a Fellow since 2020, he continues to drive advancements in CMP technology.

He is a recognized leader in the field, evidenced by his 52 published papers in journals and conferences, and has been granted 150 US patents and 213 Korean patents. He has also shared his expertise at international conferences, including keynote and invited talks at ICPT conferences in Seoul (2018), Japan (2014), and Taiwan (2013).

Beyond his work at Samsung, he participates in the broader scientific community as a Member of the ICPT Program Committee (2001–2017), the Planarization CMP Committee of JSPE (2004–Present), and formerly with Korea CMPUGM (2001–2008). He has also had the opportunity to share his knowledge through lectures at Yonsei University and Sungkyunkwan University.

In recognition of his significant contributions to the industry, he received the Silver Tower Order of Industrial Service Merit from the Korean Government in 2021, and most recently, the Outstanding Achievement Award from ICPT in 2024.